

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A method of manufacturing a circuit device, ~~in which an IC and a passive part are covered with and supported by an insulating resin,~~ using a terminal and a server which are connected to each other via a communication network, wherein the circuit device is an SIP circuit device or an ISB circuit device in which a plurality of semiconductor chips, a passive part, and a wiring are two-dimensionally placed, are electrically connected to each other, and are covered with an insulating resin,

wherein the method comprises[[ing]]:

a condition inputting step for inputting conditions including a condition of whether or not the circuit device is of a single layer structure or of a multilayer structure as conditions to be satisfied by the circuit device through the terminal and transmitting the conditions from the terminal to the server;

a manufacturing data generating step for receiving the input conditions and generating, at the server side, manufacturing data for manufacturing the circuit device based on the conditions; and

a manufacturing step for manufacturing the circuit device based on the generated manufacturing data.

2. (Currently Amended) [[A]] The method according to claim 1, further comprising:
an evaluating step for evaluating, at the server side, reliability of a circuit device to be manufactured based on the conditions when the conditions are received by the server and transmitting an evaluation result to the terminal.

3. (Currently Amended) [[A]] The method according to claim 1, wherein the conditions include at least an external size, a terminal size, a circuit diagram, IC specification data, and passive part specification data of the circuit device, and in the manufacturing data generating step, a pattern design processing and a mask design processing are performed based on the conditions for generating, as the manufacturing data, at least mask data, parts placement data, and wire bonding coordinate data.

4. (Currently Amended) [[A]] The method according to claim 1, wherein in the condition inputting step, the conditions are input through a web page which is created by the server and displayed on the terminal.

5. (Currently Amended) A method of manufacturing a circuit device, ~~in which an IC and a passive part are covered with and supported by an insulating resin,~~ using a terminal and a server which are connected to each other via a communication network, wherein the circuit device is an SIP circuit device or an ISB circuit device in which a plurality of semiconductor chips, a passive part, and a wiring are two-dimensionally placed, are electrically connected to each other, and are covered with an insulating resin,

wherein the method comprises[[ing]], at the server side, the steps of:
receiving conditions including a condition of whether or not the circuit device is of a single layer structure or of a multilayer structure as conditions to be satisfied by the circuit device from the terminal;

generating manufacturing data for manufacturing the circuit device based on the conditions; and

transmitting the generated manufacturing data to a circuit device manufacturing facility, and[[wherein]] the circuit device is manufactured using the manufacturing data in the circuit device manufacturing facility.

6. (Currently Amended) [[A]] The method according to claim 5, wherein the conditions include at least an external size, a terminal size, a circuit diagram, IC specification data, and passive part specification data of the circuit device, and the manufacturing data includes at least mask data, part arrangement data, and wire bonding coordinate data.

7. (Currently Amended) [[A]] The method according to claim 5, further comprising, at the server, the steps of:
evaluating reliability of a circuit device to be manufactured based on the conditions; and
transmitting a reliability evaluation result to the terminal.